Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment.

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm Mother Board</td>
<td>1</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries: Main battery, RTC battery</td>
<td>2</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries: LCD unit</td>
<td>1</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB / PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations. no</td>
<td>0</td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing radioactive substances</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1 Power driver</td>
<td>#1</td>
</tr>
<tr>
<td>Description #2 Trox T8 screwdriver</td>
<td>T8</td>
</tr>
<tr>
<td>Description #3 Fixture (holding support MB)</td>
<td>#1</td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Take down BTY direct from system bottom side (Get: BTY)
2. Take down HDD door/screw (get:HDD module)
3. Take down Dimm door (get: DIMM)
4. Take down bottom side screw,transfer machine to top side
5. Open lcd, take down keyboard (get: key board)
6. Cramp out t/p cable, backlight cable (get: u-case module)
7. Take down screw in base and cramp out power cable, antenna, (get: L/R I/O board, W/L, WWAN, Trim cover, lcd module)
8. Take down bezel screw/panel (get: panel)
9. Take down hinge screw & camera screw (antenna: get: hing, hinge cap, lcd bracket, camera, antenna, lcd, bezel)
10. Take down heatsink & speaker (get: heat sink, speaker)
11. Take down main board (get: M/B, L-case)
12. Take down T/P bracket / touch pad cable (get: T/P, U-case)

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
Disassemble Process-1

Get Component
1. BTY
2. HDD module
3. DI MM

Disassemble Item
a. HDD Door
b. DI MM Door
Rubber, Screw
(Tear down all screw in bottom side)
Disassemble Process-2

Get Component
4. K/B
5. u-case module

Disassemble Item
a. Screw
b. Screw (in the Top side of Base unit)
Keyboard, Cable
Disassemble Process-3

Get Component
6. t/ p bracket
7. u-case
8. t/ p

Disassemble Item
Cable, screw,
t/ p bracket
Disassemble Process-4

Get Component
9. DC-in cable
10. wwan
11. Wireless
12. R i/o board
13. L i/o board
14. Trim cover
15. Lcd module

Disassemble Item
Screw, cable
Disassemble Process-5

Get Component
16.Speaker
17.heatsink
18.M/B Module
19.L-CASE

Disassemble Item
Cable, Screw
Get Component
20.M/B
21.HDD cable

Disassemble Item
HDD Cable
Disassemble Process-7

**Get Component**
- 22. Panel
- 23. Hinge cap
- 24. Hinge
- 25. Lcd bracket
- 26. Lcd cable
- 27. Camera
- 28. Antenna
- 29. Lcd
- 30. Bezel

**Disassemble Item**
- Rubber, Screw, panel, LCD Cable, antenna